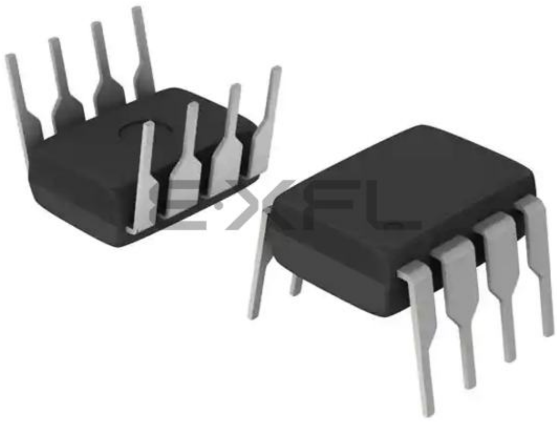
Zilog - Z8F042APB020EG Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	eZ8
Core Size	8-Bit
Speed	20MHz
Connectivity	IrDA, UART/USART
Peripherals	Brown-out Detect/Reset, LED, LVD, POR, PWM, Temp Sensor, WDT
Number of I/O	6
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Through Hole
Package / Case	8-DIP (0.300", 7.62mm)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z8f042apb020eg

List of Tables

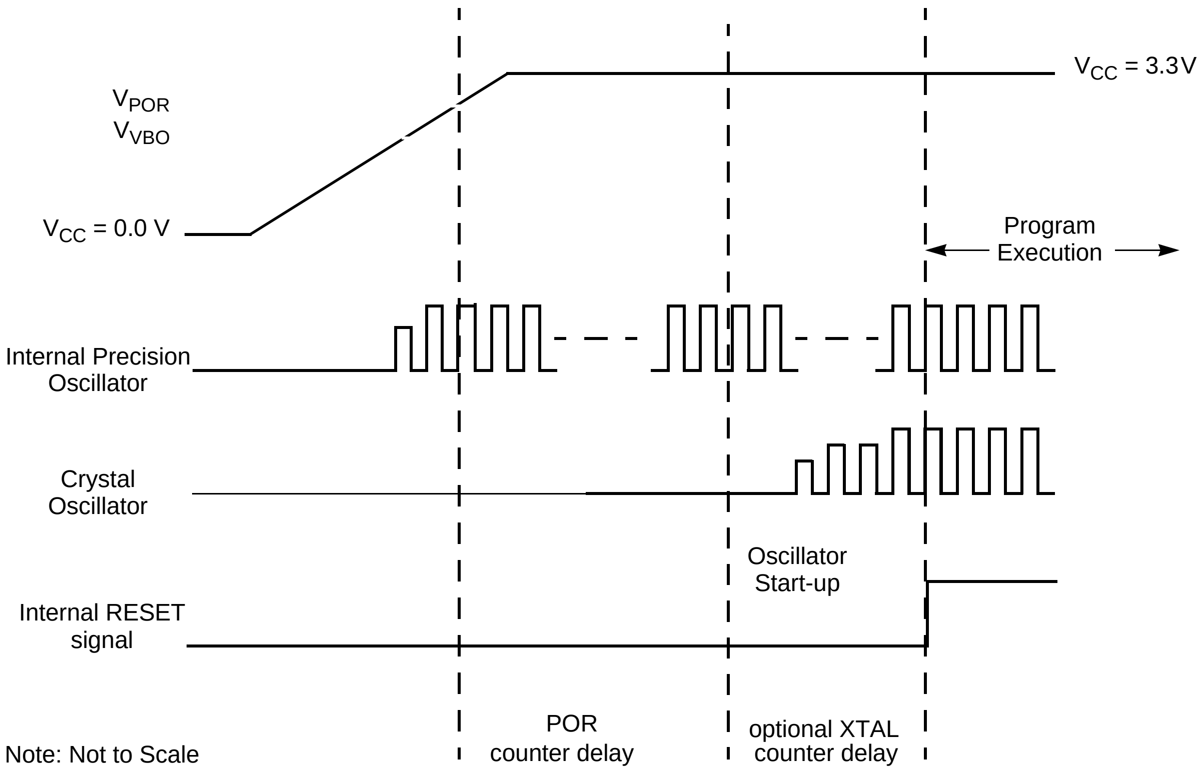

Figure 5. Power-On Reset Operation

Voltage Brown-Out Reset

The devices in the Z8 Encore! XP F082A Series provide low Voltage Brown-Out (VBO) protection. The VBO circuit senses when the supply voltage drops to an unsafe level (below the VBO threshold voltage) and forces the device into the Reset state. While the supply voltage remains below the Power-On Reset voltage threshold (V_{POR}), the VBO block holds the device in the Reset.

After the supply voltage again exceeds the Power-On Reset voltage threshold, the device progresses through a full System Reset sequence, as described in the Power-On Reset section. Following Power-On Reset, the POR status bit in the Reset Status (RSTSTAT) Register is set to 1. Figure 6 displays Voltage Brown-Out operation. See the Electrical Characteristics chapter on page 226 for the VBO and POR threshold voltages (V_{VBO} and V_{POR}).

The Voltage Brown-Out circuit can be either enabled or disabled during STOP Mode. Operation during STOP Mode is set by the VBO_AO Flash option bit. See the Flash Option Bits chapter on page 159 for information about configuring VBO_AO.

Table 11. Reset Status Register (RSTSTAT)

Bit	7	6	5	4	3	2	1	0
Field	POR	STOP	WDT	EXT	Reserved			LVD
RESET	See descriptions below			0	0	0	0	0
R/W	R	R	R	R	R	R	R	R
Address	FF0H							

Bit	Description
[7] POR	**Power-On Reset Indicator** If this bit is set to 1, a Power-On Reset event occurs. This bit is reset to 0 if a WDT time-out or Stop Mode Recovery occurs. This bit is also reset to 0 when the register is read.
[6] STOP	**Stop Mode Recovery Indicator** If this bit is set to 1, a Stop Mode Recovery occurs. If the STOP and WDT bits are both set to 1, the Stop Mode Recovery occurs because of a WDT time-out. If the STOP bit is 1 and the WDT bit is 0, the Stop Mode Recovery was not caused by a WDT time-out. This bit is reset by a Power-On Reset or a WDT time-out that occurred while not in STOP Mode. Reading this register also resets this bit.
[5] WDT	**Watchdog Timer Time-Out Indicator** If this bit is set to 1, a WDT time-out occurs. A POR resets this pin. A Stop Mode Recovery from a change in an input pin also resets this bit. Reading this register resets this bit. This read must occur before clearing the WDT interrupt.
[4] EXT	**External Reset Indicator** If this bit is set to 1, a Reset initiated by the external $\overline{\text{RESET}}$ pin occurs. A Power-On Reset or a Stop Mode Recovery from a change in an input pin resets this bit. Reading this register resets this bit.
[3:1]	**Reserved** These bits are reserved and must be programmed to 000.
[0] LVD	**Low Voltage Detection Indicator** If this bit is set to 1 the current state of the supply voltage is below the low voltage detection threshold. This value is not latched but is a real-time indicator of the supply voltage level.

Table 15. Port Alternate Function Mapping (Non 8-Pin Parts) (Continued)

Port	Pin	Mnemonic	Alternate Function Description	Alternate Function Set Register AFS1
Port B[3]	PB0	Reserved		AFS1[0]: 0
		ANA0/AMPOUT	ADC Analog Input/LPO Output	AFS1[0]: 1
	PB1	Reserved		AFS1[1]: 0
		ANA1/AMPINN	ADC Analog Input/LPO Input (N)	AFS1[1]: 1
	PB2	Reserved		AFS1[2]: 0
		ANA2/AMPINP	ADC Analog Input/LPO Input (P)	AFS1[2]: 1
	PB3	CLKIN	External Clock Input	AFS1[3]: 0
		ANA3	ADC Analog Input	AFS1[3]: 1
	PB4	Reserved		AFS1[4]: 0
		ANA7	ADC Analog Input	AFS1[4]: 1
	PB5	Reserved		AFS1[5]: 0
		V_{REF}[4]	ADC Voltage Reference	AFS1[5]: 1
	PB6	Reserved		AFS1[6]: 0
		Reserved		AFS1[6]: 1
	PB7	Reserved		AFS1[7]: 0
		Reserved		AFS1[7]: 1

Notes:

1. Because there is only a single alternate function for each Port A pin, the Alternate Function Set registers are not implemented for Port A. Enabling alternate function selections automatically enables the associated alternate function. See the Port A–D Alternate Function Subregisters (PxAF) section on page 47 for details.
2. Whether PA0/PA6 takes on the timer input or timer output complement function depends on the timer configuration. See the Timer Pin Signal Operation section on page 84 for details.
3. Because there are at most two choices of alternate function for any pin of Port B, the Alternate Function Set Register AFS2 is not used to select the function. Alternate function selection must also be enabled. See the Port A–D Alternate Function Subregisters (PxAF) section on page 47 for details.
4. V_{REF} is available on PB5 in 28-pin products and on PC2 in 20-pin parts.
5. Because there are at most two choices of alternate function for any pin of Port C, the Alternate Function Set Register AFS2 is not used to select the function. Alternate function selection must also be enabled. See the Port A–D Alternate Function Subregisters (PxAF) section on page 47 for details.
6. Because there is only a single alternate function for the Port PD0 pin, the Alternate Function Set registers are not implemented for Port D. Enabling alternate function selections automatically enables the associated alternate function. See the Port A–D Alternate Function Subregisters (PxAF) section on page 47 for details.

Rate Generator to function as an additional counter if the UART functionality is not employed.

UART Baud Rate Generator

The UART Baud Rate Generator creates a lower frequency baud rate clock for data transmission. The input to the Baud Rate Generator is the system clock. The UART Baud Rate High and Low Byte registers combine to create a 16-bit baud rate divisor value (BRG[15:0]) that sets the data transmission rate (baud rate) of the UART. The UART data rate is calculated using the following equation:

$$\text{UART Data Rate (bits/s)} = \frac{\text{System Clock Frequency (Hz)}}{16 \times \text{UART Baud Rate Divisor Value}}$$

When the UART is disabled, the Baud Rate Generator functions as a basic 16-bit timer with an interrupt upon time-out. Observe the following steps to configure the Baud Rate Generator as a timer with an interrupt upon time-out:

1. Disable the UART by clearing the REN and TEN bits in the UART Control 0 Register to 0.
2. Load the acceptable 16-bit count value into the UART Baud Rate High and Low Byte registers.
3. Enable the Baud Rate Generator timer function and associated interrupt by setting the `BRGCTL` bit in the UART Control 1 Register to 1.

When configured as a general purpose timer, the interrupt interval is calculated using the following equation:

$$\text{Interrupt Interval(s)} = \text{System Clock Period (s)} \times \text{BRG[15:0]}$$

UART Control Register Definitions

The UART Control registers support the UART and the associated Infrared Encoder/Decoders. For more information about infrared operation, see the Infrared Encoder/Decoder chapter on page 120.

UART Control 0 and Control 1 Registers

The UART Control 0 (UxCTL0) and Control 1 (UxCTL1) registers, shown in Tables 63 and 64, configure the properties of the UART's transmit and receive operations. The UART Control registers must not be written while the UART is enabled.

The UART data rate is calculated using the following equation:

$$\text{UART Baud Rate (bits/s)} = \frac{\text{System Clock Frequency (Hz)}}{16 \times \text{UART Baud Rate Divisor Value}}$$

For a given UART data rate, calculate the integer baud rate divisor value using the following equation:

$$\text{UART Baud Rate Divisor Value (BRG)} = \text{Round}\left(\frac{\text{System Clock Frequency (Hz)}}{16 \times \text{UART Data Rate (bits/s)}}\right)$$

The baud rate error relative to the acceptable baud rate is calculated using the following equation:

$$\text{UART Baud Rate Error (\%)} = 100 \times \left(\frac{\text{Actual Data Rate} - \text{Desired Data Rate}}{\text{Desired Data Rate}}\right)$$

For reliable communication, the UART baud rate error must never exceed 5 percent. Table 72 provides information about the data rate errors for popular baud rates and commonly used crystal oscillator frequencies.

Table 72. UART Baud Rates

10.0 MHz System Clock				5.5296 MHz System Clock			
Acceptable Rate (kHz)	**BRG Divisor (Decimal)**	**Actual Rate (kHz)**	**Error (%)**	**Acceptable Rate (kHz)**	**BRG Divisor (Decimal)**	**Actual Rate (kHz)**	**Error (%)**
1250.0	N/A	N/A	N/A	1250.0	N/A	N/A	N/A
625.0	1	625.0	0.00	625.0	N/A	N/A	N/A
250.0	3	208.33	–16.67	250.0	1	345.6	38.24
115.2	5	125.0	8.51	115.2	3	115.2	0.00
57.6	11	56.8	–1.36	57.6	6	57.6	0.00
38.4	16	39.1	1.73	38.4	9	38.4	0.00
19.2	33	18.9	0.16	19.2	18	19.2	0.00
9.60	65	9.62	0.16	9.60	36	9.60	0.00
4.80	130	4.81	0.16	4.80	72	4.80	0.00
2.40	260	2.40	–0.03	2.40	144	2.40	0.00
1.20	521	1.20	–0.03	1.20	288	1.20	0.00
0.60	1042	0.60	–0.03	0.60	576	0.60	0.00
0.30	2083	0.30	0.2	0.30	1152	0.30	0.00

3.579545 MHz System Clock

1.8432 MHz System Clock

Bit	Description (Continued)
[1:0]	For 8-pin devices, the following voltages can be configured; for 20- and 28-pin devices, these bits are reserved. 000000 = 0.00 V 000001 = 0.05 V 000010 = 0.10 V 000011 = 0.15 V 000100 = 0.20 V 000101 = 0.25 V 000110 = 0.30 V 000111 = 0.35 V 001000 = 0.40 V 001001 = 0.45 V 001010 = 0.50 V 001011 = 0.55 V 001100 = 0.60 V 001101 = 0.65 V 001110 = 0.70 V 001111 = 0.75 V 010000 = 0.80 V 010001 = 0.85 V 010010 = 0.90 V 010011 = 0.95 V 010100 = 1.00 V (Default) 010101 = 1.05 V 010110 = 1.10 V 010111 = 1.15 V 011000 = 1.20 V 011001 = 1.25 V 011010 = 1.30 V 011011 = 1.35 V 011100 = 1.40 V 011101 = 1.45 V 011110 = 1.50 V 011111 = 1.55 V 100000 = 1.60 V 100001 = 1.65 V 100010 = 1.70 V 100011 = 1.75 V 100100 = 1.80 V

Debugger. Writing an invalid value or an invalid sequence returns the Flash Controller to its locked state. The Write-only Flash Control Register shares its Register File address with the read-only Flash Status Register.

Table 94. LVD Trim Values

LVD_TRIM	LVD Threshold (V) Typical	Description
00000	3.60	Maximum LVD threshold
00001	3.55	
00010	3.50	
00011	3.45	
00100	3.40	
00101	3.35	
00110	3.30	
00111	3.25	
01000	3.20	
01001	3.15	
01010	3.10	Default on Reset
01011	3.05	
01100	3.00	
01101	2.95	
01110	2.90	
01111	2.85	
10000	2.80	
10001	2.75	
10010	2.70	
10011 to 11111	2.70 to 1.65	Minimum LVD threshold

Temperature Sensor Calibration Data

Table 98. Temperature Sensor Calibration High Byte at 003A (TSCALH)

Bit	7	6	5	4	3	2	1	0
Field	TSCALH							
RESET	U	U	U	U	U	U	U	U
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Address	Information Page Memory 003A							
Note: U = Unchanged by Reset. R/W = Read/Write.								

Bit	Description
[7:0] TSCALH	**Temperature Sensor Calibration High Byte** The TSCALH and TSCALL bytes combine to form the 12-bit temperature sensor offset calibration value. For more details, see Temperature Sensor Operation on page 139.

Table 99. Temperature Sensor Calibration Low Byte at 003B (TSCALL)

Bit	7	6	5	4	3	2	1	0
Field	TSCALL							
RESET	U	U	U	U	U	U	U	U
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Address	Information Page Memory 003B							
Note: U = Unchanged by Reset. R/W = Read/Write.								

Bit	Description
[7:0] TSCALL	**Temperature Sensor Calibration Low Byte** The TSCALH and TSCALL bytes combine to form the 12-bit temperature sensor offset calibration value. For usage details, see the Temperature Sensor Operation section on page 144.

enabled, the OCD ignores the BRK signal and the `BRK` instruction operates as an NOP instruction.

Breakpoints in Flash Memory

The `BRK` instruction is opcode `00H`, which corresponds to the fully programmed state of a byte in Flash memory. To implement a Breakpoint, write `00H` to the required break address, overwriting the current instruction. To remove a Breakpoint, the corresponding page of Flash memory must be erased and reprogrammed with the original data.

Runtime Counter

The On-Chip Debugger contains a 16-bit Runtime Counter. It counts system clock cycles between Breakpoints. The counter starts counting when the On-Chip Debugger leaves DEBUG Mode and stops counting when it enters DEBUG Mode again or when it reaches the maximum count of `FFFFH`.

On-Chip Debugger Commands

The host communicates to the on-chip debugger by sending OCD commands using the DBG interface. During normal operation, only a subset of the OCD commands are available. In DEBUG Mode, all OCD commands become available unless the user code and control registers are protected by programming the Flash Read Protect Option bit (FRP). The Flash Read Protect Option bit prevents the code in memory from being read out of the Z8 Encore! XP F082A Series device. When this option is enabled, several of the OCD commands are disabled. See Table 109.

Table 110 on page 191 is a summary of the on-chip debugger commands. Each OCD command is described in further detail in the bulleted list following this table. Table 110 also indicates those commands that operate when the device is not in DEBUG Mode (normal operation) and those commands that are disabled by programming the Flash Read Protect Option bit.

Table 109. Debug Command Enable/Disable

Debug Command	Command Byte	Enabled when Not in DEBUG Mode?	Disabled by Flash Read Protect Option Bit
Read OCD Revision	00H	Yes	–
Reserved	01H	–	–
Read OCD Status Register	02H	Yes	–
Read Runtime Counter	03H	–	–
Write OCD Control Register	04H	Yes	Cannot clear DBGMODE bit.
Read OCD Control Register	05H	Yes	–

When selecting a new clock source, the system clock oscillator failure detection circuitry and the Watchdog Timer oscillator failure circuitry must be disabled. If SOFEN and WOFEN are not disabled prior to a clock switch-over, it is possible to generate an interrupt for a failure of either oscillator. The Failure detection circuitry can be enabled anytime after a successful write of OSCSEL in the OSCCTL Register.

The internal precision oscillator is enabled by default. If the user code changes to a different oscillator, it may be appropriate to disable the IPO for power savings. Disabling the IPO does not occur automatically.

Clock Failure Detection and Recovery

Should an oscillator or timer fail, there are methods of recovery, as this section describes.

System Clock Oscillator Failure

The Z8F04xA family devices can generate nonmaskable interrupt-like events when the primary oscillator fails. To maintain system function in this situation, the clock failure recovery circuitry automatically forces the Watchdog Timer oscillator to drive the system clock. The Watchdog Timer oscillator must be enabled to allow the recovery. Although this oscillator runs at a much slower speed than the original system clock, the CPU continues to operate, allowing execution of a clock failure vector and software routines that either remedy the oscillator failure or issue a failure alert. This automatic switch-over is not available if the Watchdog Timer is selected as the system clock oscillator. It is also unavailable if the Watchdog Timer oscillator is disabled, though it is not necessary to enable the Watchdog Timer reset function (see the Watchdog Timer chapter on page 93).

The primary oscillator failure detection circuitry asserts if the system clock frequency drops below 1kHz ±50%. If an external signal is selected as the system oscillator, it is possible that a very slow but nonfailing clock can generate a failure condition. Under these conditions, do not enable the clock failure circuitry (SOFEN must be deasserted in the OSCCTL Register).

Watchdog Timer Failure

In the event of a Watchdog Timer oscillator failure, a similar nonmaskable interrupt-like event is issued. This event does not trigger an attendant clock switch-over, but alerts the CPU of the failure. After a Watchdog Timer failure, it is no longer possible to detect a primary oscillator failure. The failure detection circuitry does not function if the Watchdog Timer is used as the system clock oscillator or if the Watchdog Timer oscillator has been disabled. For either of these cases, it is necessary to disable the detection circuitry by deasserting the WDFEN bit of the OSCCTL Register.

The Watchdog Timer oscillator failure detection circuit counts system clocks while looking for a Watchdog Timer clock. The logic counts 8004 system clock cycles before determining that a failure has occurred. The system clock rate determines the speed at which

Table 114. Recommended Crystal Oscillator Specifications

Parameter	Value	Units	Comments
Frequency	20	MHz	
Resonance	Parallel		
Mode	Fundamental		
Series Resistance (R_S)	60	W	Maximum
Load Capacitance (C_L)	30	pF	Maximum
Shunt Capacitance (C_0)	7	pF	Maximum
Drive Level	1	mW	Maximum

Table 115. Transconductance Values for Low, Medium and High Gain Operating Modes

Mode	Crystal Frequency Range	Function	Transconductance (mA/V) (Use this range for calculations)		
Low Gain*	32kHz–1MHz	Low Power/Frequency Applications	0.02	0.04	0.09
Medium Gain*	0.5MHz–10MHz	Medium Power/Frequency Applications	0.84	1.7	3.1
High Gain*	8MHz–20MHz	High Power/Frequency Applications	1.1	2.3	4.2

Note: *Printed circuit board layouts must not add more than 4pF of stray capacitance to either the X_{IN} or X_{OUT} pins. if no oscillation occurs, reduce the values of the capacitors C1 and C2 to decrease the loading.

Internal Precision Oscillator

The internal precision oscillator (IPO) is designed for use without external components. You can either manually trim the oscillator for a nonstandard frequency or use the automatic factory-trimmed version to achieve a 5.53 MHz frequency. IPO features include:

- On-chip RC oscillator that does not require external components
- Output frequency of either 5.53 MHz or 32.8 kHz (contains both a fast and a slow mode)
- Trimmed through Flash option bits with user override
- Elimination of crystals or ceramic resonators in applications where very high timing accuracy is not required

Operation

An 8-bit trimming register, incorporated into the design, compensates for absolute variation of oscillator frequency. Once trimmed the oscillator frequency is stable and does not require subsequent calibration. Trimming is performed during manufacturing and is not necessary for you to repeat unless a frequency other than 5.53 MHz (fast mode) or 32.8 kHz (slow mode) is required. This trimming is done at +30ºC and a supply voltage of 3.3 V, so accuracy of this operating point is optimal.

If not used, the IPO can be disabled by the Oscillator Control Register (see the Oscillator Control Register Definitions section on page 196).

By default, the oscillator frequency is set by the factory trim value stored in the write-protected Flash information page. However, the user code can override these trim values as described in the Trim Bit Address Space section on page 165.

Select one of two frequencies for the oscillator (5.53 MHz and 32.8 kHz) using the OSCSEL bits in the the Oscillator Control chapter on page 193.

Assembly Language Source Program Example

`JP START`	; Everything after the semicolon is a comment.
`START:`	; A label called 'START'. The first instruction (`JP START`) in this ; example causes program execution to jump to the point within the ; program where the `START` label occurs.
`LD R4, R7`	; A Load (LD) instruction with two operands. The first operand, ; Working Register R4, is the destination. The second operand, ; Working Register R7, is the source. The contents of R7 is ; written into R4.
`LD 234H, #%01`	; Another Load (LD) instruction with two operands. ; The first operand, Extended Mode Register Address `234H`, ; identifies the destination. The second operand, Immediate Data ; value `01H`, is the source. The value `01H` is written into the ; Register at address `234H`.

Assembly Language Syntax

For proper instruction execution, eZ8 CPU assembly language syntax requires that the operands be written as 'destination, source'. After assembly, the object code usually has the operands in the order 'source, destination', but ordering is opcode-dependent. The following instruction examples illustrate the format of some basic assembly instructions and the resulting object code produced by the assembler. This binary format must be followed if manual program coding is preferred or if you intend to implement your own assembler.

Example 1. If the contents of registers `43H` and `08H` are added and the result is stored in `43H`, the assembly syntax and resulting object code is:

Table 116. Assembly Language Syntax Example 1

Assembly Language Code	ADD	43H,	08H	(ADD dst, src)
Object Code	04	08	43	(OPC src, dst)

Example 2. In general, when an instruction format requires an 8-bit register address, that address can specify any register location in the range 0–255 or, using Escaped Mode Addressing, a Working Register R0–R15. If the contents of Register 43H and Working Register R8 are added and the result is stored in `43H`, the assembly syntax and resulting object code is:

Table 117. Assembly Language Syntax Example 2

Assembly Language Code	ADD	43H,	R8	(ADD dst, src)
Object Code	04	E8	43	(OPC src, dst)

On-Chip Debugger Timing

Figure 36 and Table 145 provide timing information for the DBG pin. The DBG pin timing specifications assume a 4 ns maximum rise and fall time.

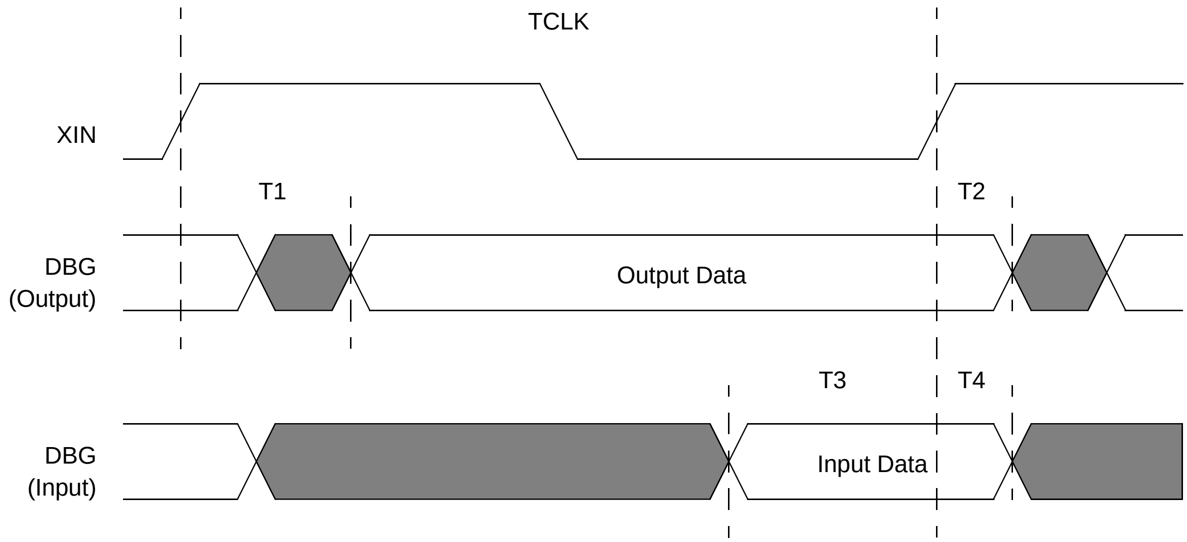

Figure 36. On-Chip Debugger Timing

Table 145. On-Chip Debugger Timing

		Delay (ns)	
Parameter	**Abbreviation**	**Minimum**	**Maximum**
DBG			
T_1	X_{IN} Rise to DBG Valid Delay	–	15
T_2	X_{IN} Rise to DBG Output Hold Time	2	–
T_3	DBG to XIN Rise Input Setup Time	5	–
T_4	DBG to XIN Rise Input Hold Time	5	–

Figure 38 and Table 147 provide timing information for UART pins for the case where CTS is not used for flow control. DE asserts after the Transmit Data Register has been written. DE remains asserted for multiple characters as long as the Transmit Data Register is written with the next character before the current character has completed.

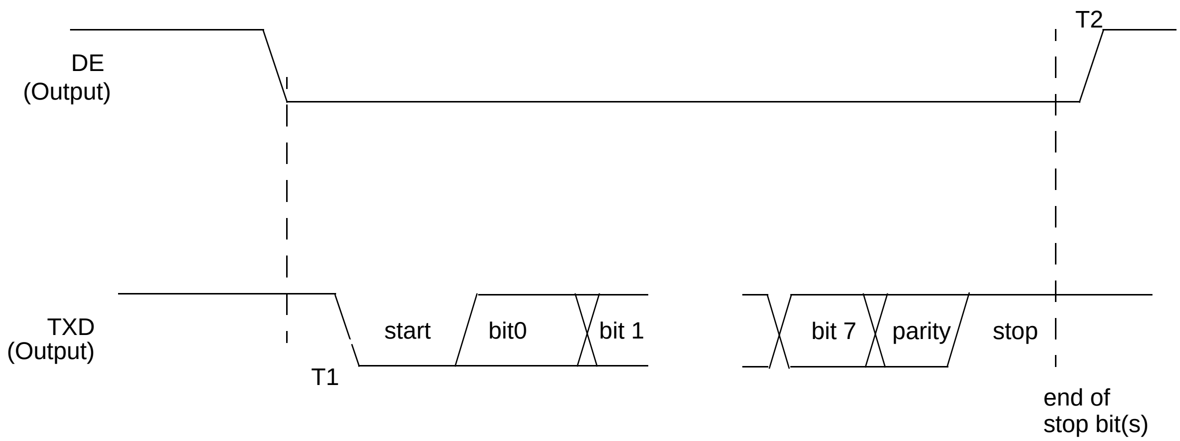

Figure 38. UART Timing Without CTS

Table 147. UART Timing Without CTS

Parameter	Abbreviation	Delay (ns) Minimum	Delay (ns) Maximum
UART			
T_1	DE assertion to TXD falling edge (start bit) delay	1 * X_{IN} period	1 bit time
T_2	End of Stop Bit(s) to DE deassertion delay (Tx Data Register is empty)	± 5	

Table 148. Z8 Encore! XP F082A Series Ordering Matrix

Part Number	Flash	RAM	NVDS	I/O Lines	Interrupts	16-Bit Timers w/PWM	10-Bit A/D Channels	UART with IrDA	Comparator	Temperature Sensor	Description
Z8 Encore! XP F082A Series with 2 KB Flash											
Standard Temperature: 0°C to 70°C											
Z8F021APB020SG	2 KB	512 B	64 B	6	13	2	0	1	1	0	PDIP 8-pin package
Z8F021AQB020SG	2 KB	512 B	64 B	6	13	2	0	1	1	0	QFN 8-pin package
Z8F021ASB020SG	2 KB	512 B	64 B	6	13	2	0	1	1	0	SOIC 8-pin package
Z8F021ASH020SG	2 KB	512 B	64 B	17	19	2	0	1	1	0	SOIC 20-pin package
Z8F021AHH020SG	2 KB	512 B	64 B	17	19	2	0	1	1	0	SSOP 20-pin package
Z8F021APH020SG	2 KB	512 B	64 B	17	19	2	0	1	1	0	PDIP 20-pin package
Z8F021ASJ020SG	2 KB	512 B	64 B	25	19	2	0	1	1	0	SOIC 28-pin package
Z8F021AHJ020SG	2 KB	512 B	64 B	25	19	2	0	1	1	0	SSOP 28-pin package
Z8F021APJ020SG	2 KB	512 B	64 B	25	19	2	0	1	1	0	PDIP 28-pin package
Extended Temperature: –40°C to 105°C											
Z8F021APB020EG	2 KB	512 B	64 B	6	13	2	0	1	1	0	PDIP 8-pin package
Z8F021AQB020EG	2 KB	512 B	64 B	6	13	2	0	1	1	0	QFN 8-pin package
Z8F021ASB020EG	2 KB	512 B	64 B	6	13	2	0	1	1	0	SOIC 8-pin package
Z8F021ASH020EG	2 KB	512 B	64 B	17	19	2	0	1	1	0	SOIC 20-pin package
Z8F021AHH020EG	2 KB	512 B	64 B	17	19	2	0	1	1	0	SSOP 20-pin package
Z8F021APH020EG	2 KB	512 B	64 B	17	19	2	0	1	1	0	PDIP 20-pin package
Z8F021ASJ020EG	2 KB	512 B	64 B	25	19	2	0	1	1	0	SOIC 28-pin package
Z8F021AHJ020EG	2 KB	512 B	64 B	25	19	2	0	1	1	0	SSOP 28-pin package
Z8F021APJ020EG	2 KB	512 B	64 B	25	19	2	0	1	1	0	PDIP 28-pin package

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